

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: David A. Baldwin :
and Todd L. Hylton :
: Attorney Docket No.: 53757-5013
Serial No.: Not yet known :
Filed: March 29, 2004 :
For: System And Method For Performing :
Sputter Etching Using Independent :
Ion And Electron Sources And A :
Substrate Biased With An :
A-Symmetric Bi-Polar DC Pulse :
Signal :

NEW APPLICATION TRANSMITTAL

Mail Stop PATENT APPLICATION
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Enclosed for filing is a new application for the above-entitled invention.

The complete application consists of 17 pages including:

15 pages of specification text;
3 pages of claims;
1 page of abstract; and
2 sheets of formal drawings.

The inventors for this application are: David Alan Baldwin, 4803 Autumn Lake Way, Annandale, Virginia 22003 and Todd Lanier Hylton, 705 Crown Meadow Drive, Great Falls, Virginia 22066. Both inventors are citizens of the United States of America.

EXPRESS MAIL CERTIFICATE (37 C.F.R. § 1.10)

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Date of Deposit March 29, 2004

I hereby certify that this paper, and the papers and/or fees referred to herein as transmitted, submitted or enclosed, are being deposited with the U.S. Postal Service "Express Mail Post Office to Addressee" service under 37 C.F.R. § 1.10 on the date indicated above and is addressed to the Mail Stop Patent Application, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

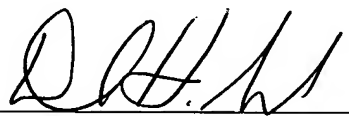
Name Daniel H. Golub

Signature 

The present application is a continuation-in-part of U.S. Patent Appl. Serial No. 10/200,578, filed July 22, 2002, entitled "System and Method for Performing Thin Film Deposition or Chemical Treatment Using an Energetic Flux of Neutral Reactive Molecular Fragments, Atoms or Radicals" (incorporated herein by reference), which is a continuation-in-part of U.S. Patent Appl. Serial No. 10/137,897, filed May 2, 2002, entitled "System and Method for Performing Sputter Deposition With Multiple Targets Using Independent Ion and Electron Sources and Target Biasing with DC Pulse Signals" (incorporated herein by reference), which is a continuation-in-part of U.S. Patent No. 6,402,904, filed March 16, 2001, entitled "System and Method for Performing Sputter Deposition Using Independent Ion and Electron Current Sources and a Target Biased with an A-Symmetric Bi-Polar DC Pulse Signal" (incorporated herein by reference) and a continuation-in-part of U.S. Patent No. 6,402,900 filed March 16, 2001, entitled "System and Method for Performing Sputter Deposition Using Ion Sources, Targets and Substrate Arranged About the Faces of a Cube."

It is respectfully submitted that a Notice to File Missing Parts be directed to the undersigned.

Respectfully submitted,



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Dated: March 29, 2004